

Figure 8: Scatter plot of fitted data versus raw data (screening experiment)

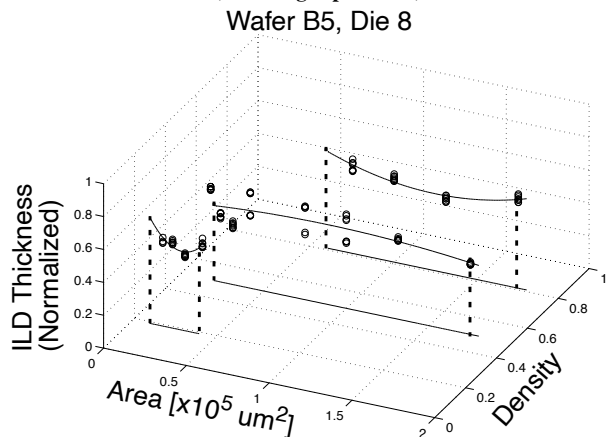


Figure 9: Thickness versus area and density for a particular die

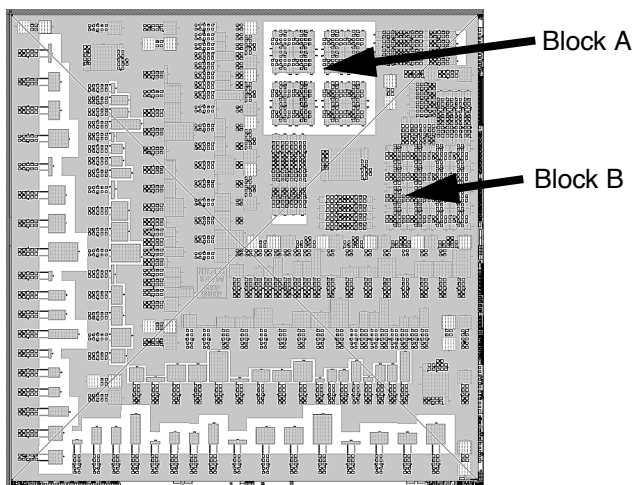


Figure 10: A 1.5cm x 1.5cm short-flow test mask used in the environment/modeling experiment.

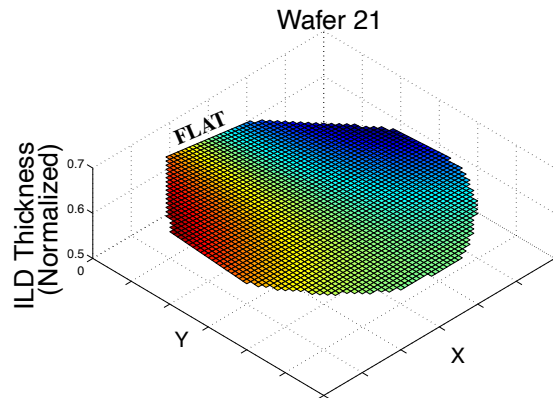


Figure 11: The extracted wafer-level variation (modeling experiment)

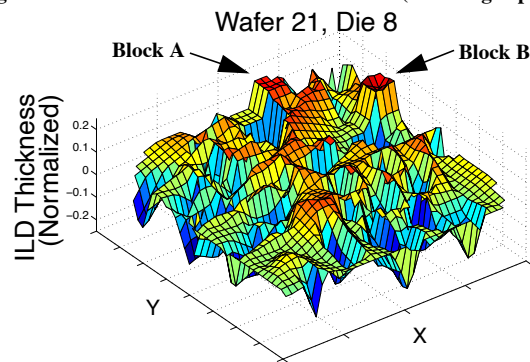


Figure 12: The extracted die-level variation (modeling experiment)

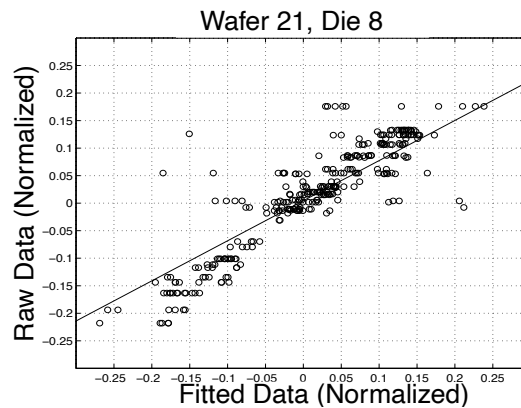


Figure 13: Scatter plot fitted data versus raw data (modeling experiment)

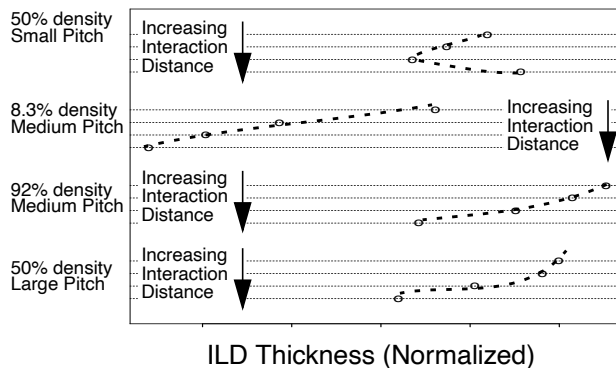


Figure 14: ILD thickness versus density, pitch, and interaction distance for the modeling/environment experiment.

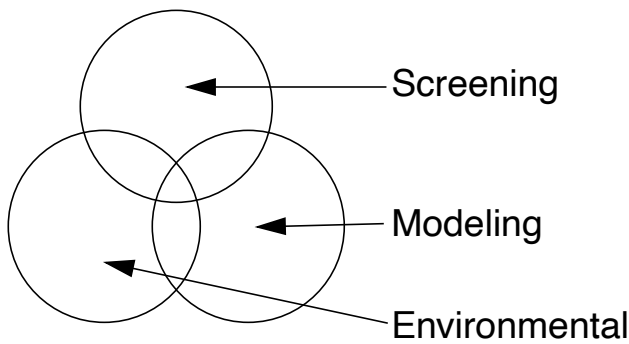


Figure 1: The three types of experiments needed for the variation assessment phase of Statistical Metrology

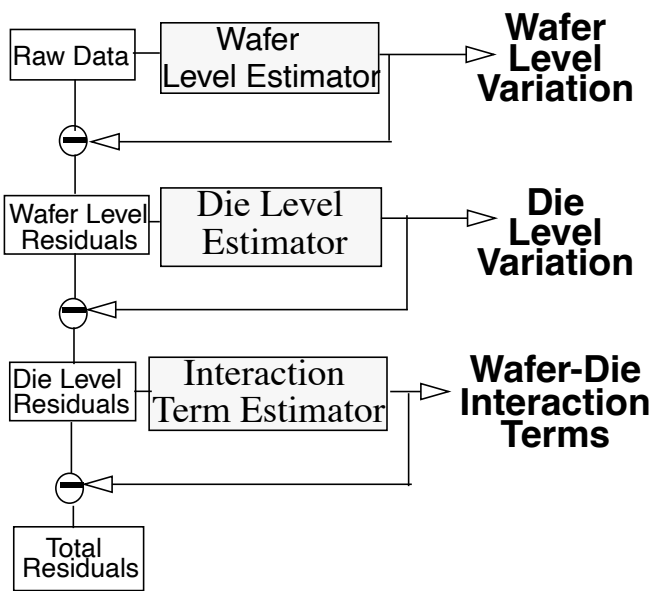


Figure 2: The variation decomposition method flowchart

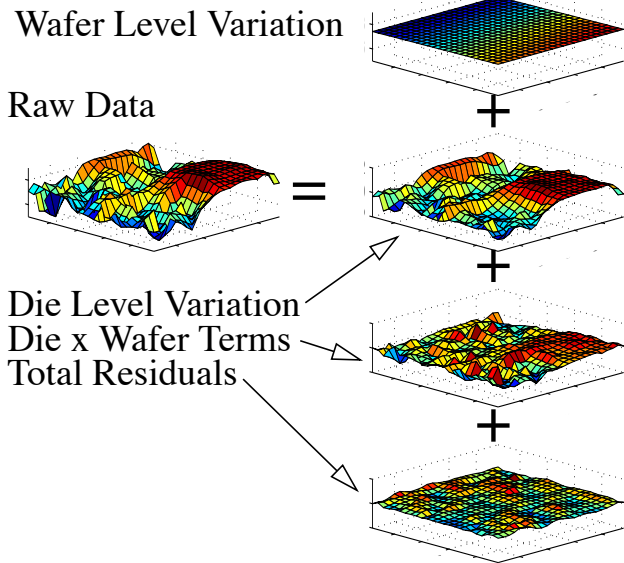


Figure 3: Variation decomposition example for one particular die showing the additive property of the model.

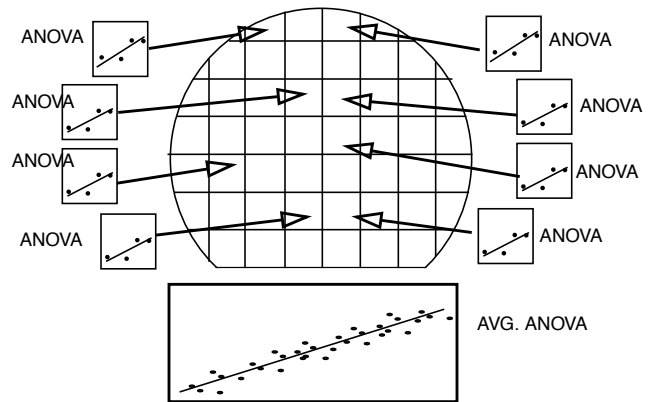


Figure 4: Repeated measure ANOVA showing connection between individual die models and overall mean model

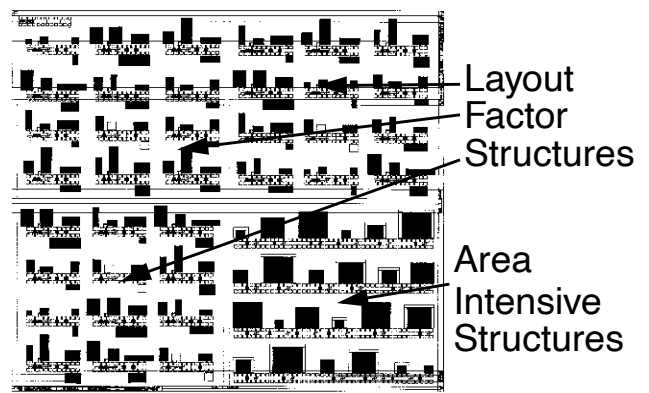


Figure 5: A 1.45cm x 1.45cm short-flow test mask used for the screening experiment Wafer B5

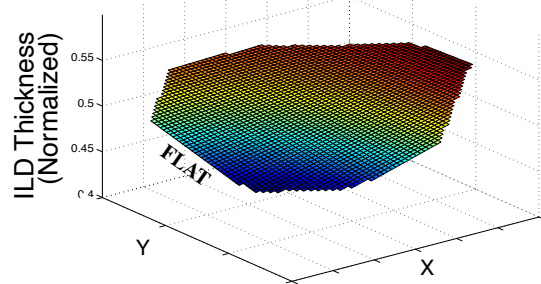


Figure 6: The extracted wafer-level variation (screening experiment) Wafer B5, Die 8

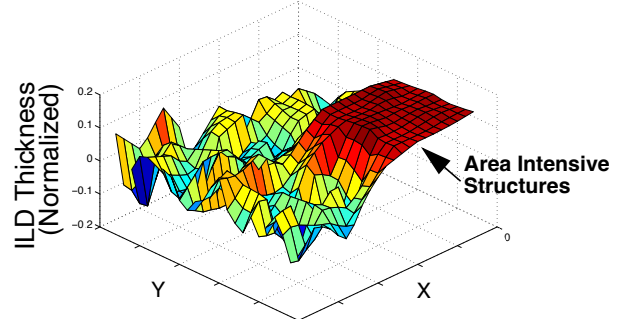


Figure 7: The extracted die-level variation (screening experiment)